

Amendment
Application No. 10/602,906
Attorney Docket No. 052455

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions of claims in the application.

Listing of Claims

Claim 1 (currently amended): A composition for forming a transparent conducting film, the composition comprising a water-soluble indium compound, a halogen-containing water-soluble organotin compound and a water-soluble organic high molecular weight compound.

Claim 2 (original): The composition according to claim 1, wherein the halogen-containing water-soluble organotin compound is one in which a first endothermic peak temperature in a differential thermal analysis curve is 75 °C or higher.

Claim 3 (original): The composition according to claim 1, wherein the difference between the first endothermic peak temperature of the water-soluble indium compound and the first endothermic peak temperature of the halogen-containing water-soluble organotin compound in the differential thermal analysis curve is 100 °C or less.

Claim 4 (original): A solution for forming a transparent conducting film, the solution having the composition of claim 1, 2 or 3 dissolved in water or a solvent comprising water and an organic solvent.

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Claim 5 (currently amended): The solution according to claim 4, wherein water is present in a ratio of 10 to 100 wt. % based on the total solvent, and the water-soluble organic high molecular weight compound is present in a ratio of ~~[[0.03]]~~ 1 to 10 wt. % based on the total solution.

Claim 6 (original): The solution according to claim 4 which has a surface tension of 20 to 70 mN/m and a viscosity of 20 mPa·s or less.

Claim 7 (original): A method for forming a transparent conducting film, which comprises the steps of

- (1) applying the solution of claim 4 onto a substrate, and
- (2) firing the coating film.

Claim 8 (original): The method according to claim 7, wherein the firing is carried out in an atmosphere which has higher partial oxygen pressure than air in step (2).

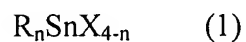
Claim 9 (original): The method according to claim 7, which further comprises a step of subjecting the film obtained in step (2) to a reducing heat treatment.

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Claim 10 (currently amended): The method according to claim 7, wherein the solution of step (1) has water in a ratio of 10 to 100 wt. % based on the total solvent, and has the water-soluble organic high molecular weight compound in a ratio of 0.03 to 10 wt. % based on the total solution.

Claim 11 (original): The method according to claim 7, wherein the solution of step (1) has a surface tension of 20 to 70 mN/m and a viscosity of 20 mPa·s or less.

Claim 12 (new): The composition according to claim 1, wherein the halogen-containing water-soluble organotin compound is at least one compound selected from the group consisting of compounds represented by the formula (1)



wherein R is an alkyl group having 1 to 3 carbon atoms, X is a halogen atom and n is an integer from 1 to 3.

Claim 13 (new): The composition according to claim 1, wherein the halogen-containing water-soluble organotin compound is dimethyltin dichloride.

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Claim 14 (new): The composition according to claim 1, wherein the water-soluble indium compound is at least one compound selected from the group consisting of indium chloride, indium nitrate, indium perchlorate, and indium sulfate.

Claim 15 (new): The composition according to claim 1, wherein the halogen-containing water-soluble organotin compound is dimethyltin dichloride and water-soluble indium compound is indium chloride trihydrate or indium nitrate trihydrate.

Claim 16 (new): The composition according to claim 1, wherein the water-soluble organic high molecular weight compound is at least one compound selected from the group consisting of polyvinyl alcohol, polyethylene glycol and polyvinyl pyrrolidone.